CDM L Series Modular Data Center:

Designed for high-density AI and HPC applications.

The CDM L Series is a purpose-built modular data center designed and built in the USA to support ultra-high-density AI training and HPC workloads. Engineered for 50–250+ kW per rack and scalable from 1.5 to 3+ MW per instance, its dual-module architecture delivers powerful performance for next-generation AI applications. With a customizable base model and open OEM integration, the CDM L Series enables fast, flexible deployment and seamless scalability.

Key Features:

- **High Density:** Supports 50–250+ kW per rack, scalable to 1.5–3+ MW per dual module.
- **Advanced Cooling:** Direct-to-chip liquid, overhead AHU, immersion, and CDU options.
- **AI-Ready:** Ideal for GPU clusters, hyperscale AI/ML, HPC, and digital twin workloads.
- **Open OEM Integration:** Compatible with leading chip and IT hardware manufacturers.
- **Certified & Rugged:** UL2755, NEMA Rated, seismic, wind, and snow ratings.

AI & HPC Expertise at Scale.

Optimized for ultra-high-density compute, the L Series combines cutting-edge power and cooling design to accelerate AI learning workloads at scale. With flexible thermal architectures—including direct-to-chip liquid and hybrid air-liquid cooling—it ensures efficiency, resiliency, and adaptability for Hyperscalers, HPC facilities, AI labs, Government facilities seeking to future-proof their infrastructure.

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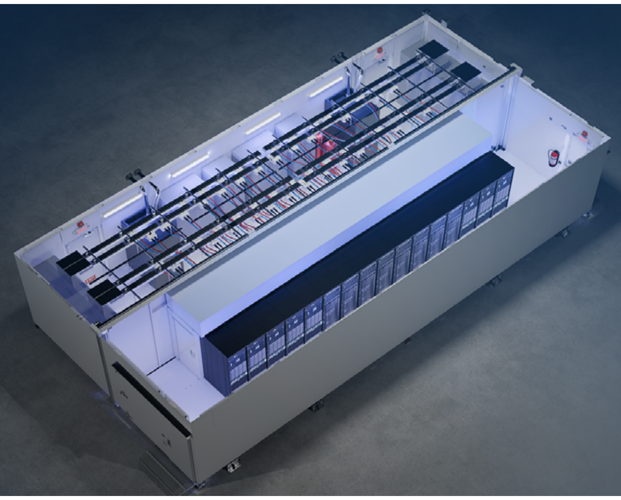
Features	CDM L Series Specifications
Dimensions (approx.):	• IT Module: 45’ L, 11’ W, 12’ H • Utility Module: 45’ L, 11’ W, 12’ H • Overhead Cooling Module: 45’ L, 11’ W, 4’ H
Rack Density:	Engineered for 50–250+ kW per rack.
Total Capacity:	Scalable to 1.5–3 MW. Dual-module architecture with overhead cooling module.
Cooling:	• Direct-to-chip liquid • Overhead AHU • Hybrid air/liquid • Under floor dual loop piping for liquid cooling • Supports multiple CDU/cold plate cooling solutions • Supports chilled water air cooling at 600kW max
Power:	Flexible busway or Optional power cable support. 480V/415V standard, 208V optional.
Weight:	Utility Module 70,000 lbs, IT Module 60,000 lbs., Top Hat AHU: 15,000 lbs., 8-point bottom lift.
Deployment Speed:	30–50% faster than traditional stick-built data centers.
Compliance:	UL2755 compliance, NEMA rated, meets Seismic C; sustains wind speeds up to 120 mph; snow loads up to 30 PSF; can be configured for higher environmental requirements.
OEM Compatibility:	Supports multiple chip, IT hardware and infrastructure OEM equipment with no vendor lock-in, allowing customers to determine best technology for their application.
Reliability:	Supports Tier 1–4 architectures for uptime and redundancy.
Lifecycle Services:	Conceptualization and design, Industrial fabrication, Factory acceptance testing (FAT), Deployment and commissioning, Long-term maintenance and SLAs.
Technology Neutral:	Supports multiple IT hardware and infrastructure OEM equipment with no vendor lock-in, allowing customers to determine best technology for their application.



Built for Scale. Engineered for Performance.

Adaptable for future AI hardware and workload evolution, the L Series delivers unmatched density, thermal efficiency, and speed for AI training needs.

With unparalleled expertise, adaptability, and innovative technology, we deliver vendor-agnostic solutions that meet the growing demands of AI and high-performance computing.

Let’s drive modular innovation and efficiency – together.

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For full solutions details, visit https://cd-modular.com